Product Preview

Dual Inverter

The NL27WZ04 is a high performance dual inverter operating from a 2.3 to 5.5 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance.

Current drive capability is 24 mA at the outputs.

- Extremely High Speed: t_{PD} 2.0 ns (typical) at $V_{CC} = 5 \text{ V}$
- Designed for 2.3 V to 5.5 V V_{CC} Operation
- Over Voltage Tolerant Inputs
- LVTTL Compatible Interface Capability With 5 V TTL Logic with V_{CC} = 3 V
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current Substantially Reduces System Power Requirements
- Replacement for NC7W04

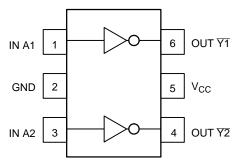


Figure 1. 6-Lead SOT-363 Pinout (Top View)

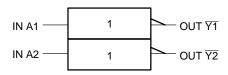


Figure 2. Logic Symbol

PIN ASSIGNMENT

1	IN A1
2	GND
3	IN A2
4	OUT Y2
5	Vcc
6	OUT Y1

FUNCTION TABLE

A Input	▼ Output
L H	H L

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.



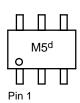
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SC-88 / SOT-363/SC-70 DF SUFFIX CASE 419B



d = Date Code





d = Date Code

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS (Note 1.)

Symbol	Parameter	Condition	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
VI	DC Input Voltage		$-0.5 \le V_1 \le +7.0$	V
Vo	DC Output Voltage	Output in HIGH or LOW State.(Note 3.)	$-0.5 \le V_{O} \le V_{CC} + 0.5$	V
I _{IK}	DC Input Diode Current	V _I < GND	– 50	mA
l _{OK}	DC Output Diode Current	V _O < GND	– 50	mA
		V _O > V _{CC}	+50	mA
Io	DC Output Source/Sink Current		±50	mA
Icc	DC Supply Current Per Supply Pin		±100	mA
I _{GND}	DC Ground Current Per Ground Pin		±100	mA
T _{STG}	Storage Temperature Range		-65 to +150	°C
P _D	Power Dissipation in Still Air SC–88, TSOP–6	per derating (Note 2.)	200	mW
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 4.) Machine Model (Note 5.) Charged Device Model (Note 6.)	> 2000 > 200 > 3000	V
I _{Latch-Up}	Latch-Up Performance	Above V _{CC} and Below GND at 85°C (Note 7.)	±500	mA

^{1.} Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute-maximum-rated conditions is not implied.

- 2. Derating SC–88 Package: –3 mW/°C from 65° to 125°C TSOP–6 Package: –5 mW/°C from 65° to 125°C

 3. Io absolute maximum rating must be observed.

 4. Tested to EIA/JESD22–A114–A

- 5. Tested to EIA/JESD22–A115–A6. Tested to JESD22–C101–A
- 7. Tested to EIA/JESD78

RECOMMENDED OPERATING CONDITIONS

Symbol	Paramete	Min	Max	Unit	
V _{CC}	Supply Voltage	Supply Voltage Operating Data Retention Only		5.5 5.5	V
VI	Input Voltage		0	5.5	V
Vo	Output Voltage	(HIGH or LOW State)	0	V _{CC}	V
ГОН	HIGH Level Output Current	$V_{CC} = 4.5 \text{ V} - 5.5 \text{ V}$ $V_{CC} = 3.0 \text{ V} - 3.6 \text{ V}$ $V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$ $V_{CC} = 2.3 \text{ V} - 2.7 \text{ V}$		- 32 - 24 - 12 - 8	mA
l _{OL}	LOW Level Output Current	$V_{CC} = 4.5 \text{ V} - 5.5 \text{ V}$ $V_{CC} = 3.0 \text{ V} - 3.6 \text{ V}$ $V_{CC} = 2.7 \text{ V} - 3.0 \text{ V}$ $V_{CC} = 2.3 \text{ V} - 2.7 \text{ V}$		+ 32 + 24 + 12 + 8	mA
T _A	Operating Free-Air Temperature		-40	+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ $V_{CC} = 3.0 \text{ V} \pm 0.3 \text{ V}$ $V_{CC} = 5.0 \text{ V} \pm 0.5 \text{ V}$	0 0 0	20 10 5	ns/V

The θ_{JA} of the package is equal to 1/Derating. Higher junction temperatures may affect the expected lifetime of the device per the table and figure below.

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

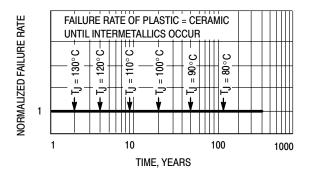


Figure 3. Failure Rate vs. Time Junction Temperature

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	1	_A = 25°(;	$T_A \le$	85°C	
Symbol	Parameter	Condition	(V)	Min	Тур	Max	Min	Max	Unit
V _{IH}	Minimum High-Level Input Voltage		2.3 to 5.5	0.7 V _{CC}			0.7 V _{CC}		V
V _{IL}	Maximum Low-Level Input Voltage		2.3 to 5.5			0.3 V _{CC}		0.3 V _{CC}	٧
V _{OH}	Minimum High-Level Output Voltage VIN = VIH or VII	I _{OH} = 100 μA	2.3 to 5.5	V _{CC} – 0.1	V _{CC}		V _{CC} – 0.1		V
	- IIV - III IIC	I _{OH} = -8 mA	2.3	1.9	TBD		1.9		
		I _{OH} = -12 mA	2.7	2.2	TBD		2.2		
		I _{OH} = -16 mA	3.0	2.4	TBD		2.4		
		I _{OH} = -24 mA	3.0	2.3	TBD		2.3		
		I _{OH} = -32 mA	4.5	3.8	TBD		3.8		
V _{OL}	Maximum Low-Level Output Voltage	I _{OL} = 100 μA	2.3 to 5.5			0.1		0.1	V
	$V_{IN} = V_{IH}$ or V_{IL}	I _{OL} = 8 mA	2.3		TBD	0.3		0.3	
		I _{OL} = 12 mA	2.7		TBD	0.4		0.4	-
		I _{OL} = 16 mA	3.0		TBD	0.4		0.4	-
		I _{OL} = 24 mA	3.0		TBD	0.55		0.55	•
		I _{OL} = 32 mA	4.5		TBD	0.55		0.55	
I _{IN}	Maximum Input Leakage Current	V _{IN} or V _{OUT} = V _{CC} or GND	0 to 5.5			±0.1		±0.1	μΑ
I _{OFF}	Maximum Off-State Leakage Current	V _{OUT} = 5.5 V	0			1		10	nA
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	5.5			1		10	μΑ

AC ELECTRICAL CHARACTERISTICS t_R = t_F = 2.5 ns; C_L = 50 pF; R_L = 500 Ω

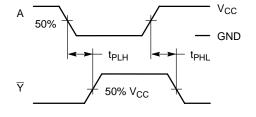
				7	Γ _A = 25°(;	T _A ≤	85°C	
Symbol	Parameter	Condition	V _{CC} (V)	Min	Тур	Max	Min	Max	Unit
t _{PLH}	Maximum Propagation Delay	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	2.5 ± 0.2	1.2	3.0	5.1	1.2	5.6	ns
t _{PHL}	HL Input A to ♥ Figure 4. and 5.	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	3.3 ± 0.3	0.8	2.2	3.4	0.8	3.8	
		$R_L = 500 \ \Omega, C_L = 50 \ pF$		1.2	2.9	4.5	1.2	5.0	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	5.0 ± 0.5	0.5	18	2.8	0.5	3.1	
		$R_L = 500 \ \Omega, C_L = 50 \ pF$		0.8	2.3	3.6	0.8	4.0	
toslh	Output-to-Output Skew	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	2.5 ± 0.2			1.0		1.0	ns
toshl	(Note 8.)	$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	3.3 ± 0.3			1.0		1.0	
		$R_L = 500 \ \Omega, C_L = 50 \ pF$				1.0		1.0	
		$R_L = 1 \text{ M}\Omega, C_L = 15 \text{ pF}$	5.0 ± 0.5			1.0		1.0	
		$R_L = 500 \Omega, C_L = 50 pF$				1.0		1.0	

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t_{OSHL}) or LOW-to-HIGH (t_{OSLH}); parameter guaranteed by design.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	7	pF
C _{OUT}	Output Capacitance	V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	8	pF
C _{PD}	Power Dissipation Capacitance (Note 9.)	10 MHz, V_{CC} = 5.5 V, V_{I} = 0 V or V_{CC}	25	pF

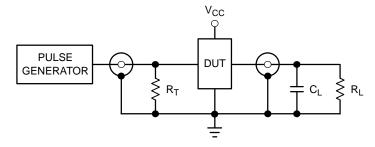
C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I_{CC(OPR)} = C_{PD} • V_{CC} • f_{in} + I_{CC}. C_{PD} is used to determine the no–load dynamic power consumption; P_D = C_{PD} • V_{CC}² • f_{in} + I_{CC} • V_{CC}.



PROPAGATION DELAYS

 t_R = t_F = 2.5 ns, 10% to 90%; f = 1 MHz; t_W = 500 ns

Figure 4. Switching Waveforms



 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 5. Test Circuit

DEVICE ORDERING INFORMATION

			Devi						
Device Order Number	Logic Circuit Indicator	No. of Gates per Package	Temp Range Identifier	Technology	Device Function	Package Suffix	Tape & Reel Suffix	Package Type (Name/SOT#/ Common Name)	Tape and Reel Size
NL27WZ04DFT2	NL	2	7	WZ	04	DF	T2	SC-88 / SOT-363 / SC-70	178 mm (7") 3000 Unit
NL27WZ04DFT4	NL	2	7	WZ	04	DF	T4	SC-88 / SOT-363 / SC-70	330 mm (13") 10000 Unit
NL27WZ04DTT1	NL	2	7	WZ	04	DT	T1	TSOP-6 / SOT-23 / SC-59	178 mm (7") 3000 Unit
NL27WZ04DTT3	NL	2	7	WZ	04	DT	Т3	TSOP-6 / SOT-23 / SC-59	330 mm (13") 10000 Unit

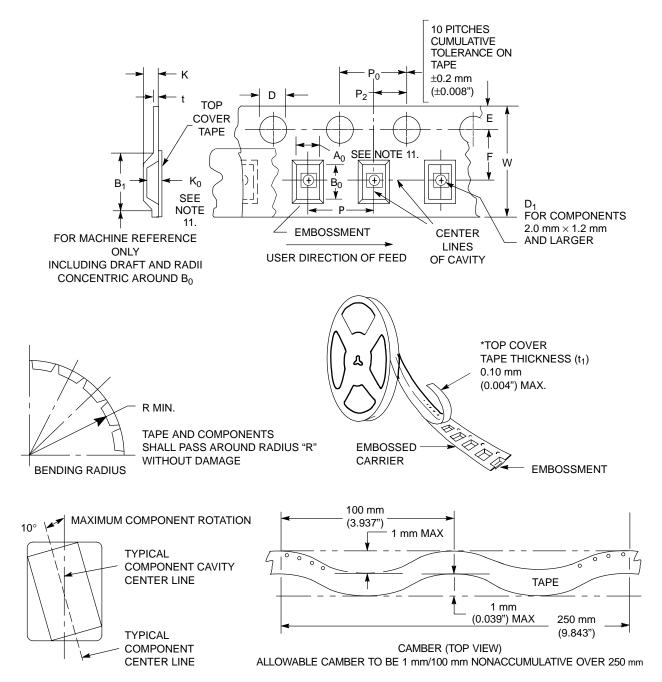


Figure 6. Carrier Tape Specifications

EMBOSSED CARRIER DIMENSIONS (See Notes 10. and 11.)

Tape Size	B ₁ Max	D	D ₁	E	F	К	Р	P ₀	P ₂	R	Т	w
8 mm	4.35 mm (0.171")	1.5 +0.1/ -0.0 mm (0.059 +0.004/ -0.0")	1.0 mm Min (0.039")	1.75 ±0.1 mm (0.069 ±0.004")	3.5 ±0.5 mm (1.38 ±0.002")	2.4 mm (0.094")	4.0 ±0.10 mm (0.157 ±0.004")	4.0 ±0.1 mm (0.156 ±0.004")	2.0 ±0.1 mm (0.079 ±0.002")	25 mm (0.98")	0.3 ±0.05 mm (0.01 +0.0038/ -0.0002")	8.0 ±0.3 mm (0.315 ±0.012")

^{10.} Metric Dimensions Govern-English are in parentheses for reference only.

^{11.} A₀, B₀, and K₀ are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

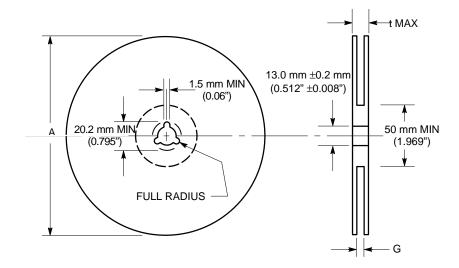


Figure 7. Reel Dimensions

REEL DIMENSIONS

Tape Size	T&R Suffix	A Max	G	t Max
8 mm	T1, T2	178 mm (7")	8.4 mm, +1.5 mm, -0.0 (0.33" + 0.059", -0.00)	14.4 mm (0.56")
8 mm	T3, T4	330 mm (13")	8.4 mm, +1.5 mm, -0.0 (0.33" + 0.059", -0.00)	14.4 mm (0.56")

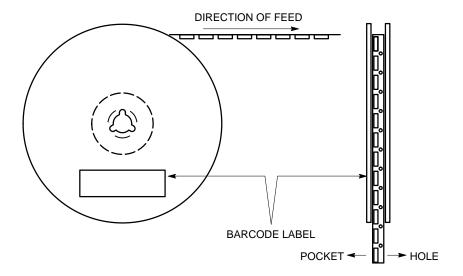


Figure 8. Reel Winding Direction

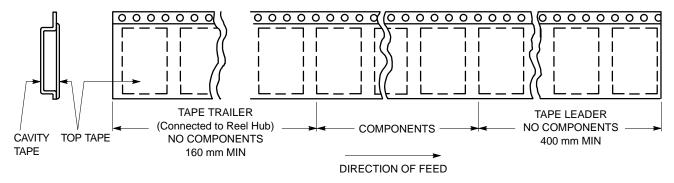


Figure 9. Tape Ends for Finished Goods

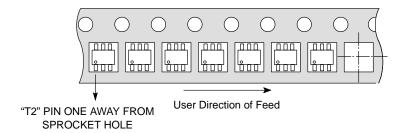


Figure 10. DFT2 and DFT4 (SC88) Reel Configuration/Orientation

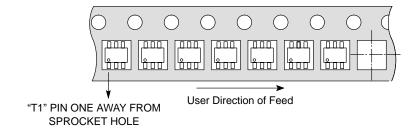
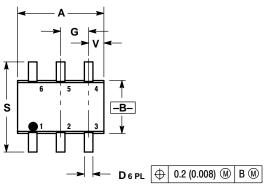


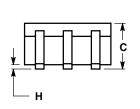
Figure 11. DTT1 and DTT3 (TSOP6) Reel Configuration/Orientation

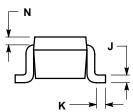
PACKAGE DIMENSIONS

SC-88/SOT-363/SC-70 **DF SUFFIX** CASE 419B-01 ISSUE G

SCALE 4:1

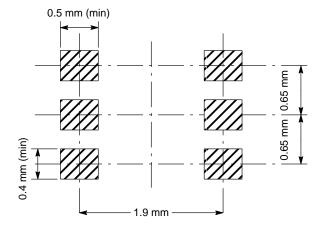






- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.071	0.087	1.80	2.20
В	0.045	0.053	1.15	1.35
С	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026	BSC	0.65	BSC
Н		0.004		0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008	0.008 REF		REF
S	0.079	0.087	2.00	2.20
V	0.012	0.016	0.30	0.40

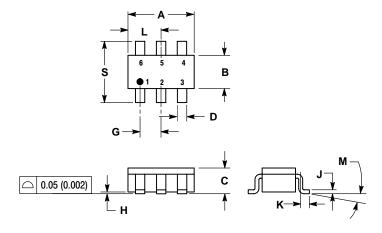


PACKAGE DIMENSIONS

TSOP-6/SOT-23/SC-59 **DT SUFFIX**

CASE 318G-02 **ISSUE G**

SCALE 2:1



STYLE 1:
PIN 1. DRAIN
2. DRAIN
3. GATE
4. SOURCE
5. DRAIN
6. DRAIN

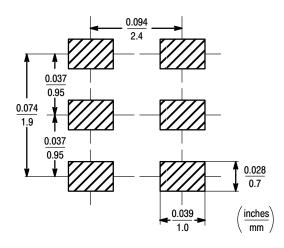
STYLE 2:
PIN 1. EMITTER 2
2. BASE 1
3. COLLECTOR 1
4. EMITTER 1
5. BASE 2
6. COLLECTOR 2

STYLE 3:
PIN 1. ENABLE
2. N/C
3. R BOOST
4. Vz
5. V in
6. V out

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.05	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
M	0 °	10°	0 °	10°
9	2 50	3.00	0.0085	0.1181

STYLE 4:
PIN 1. N/C
2. V in
3. NOT USED
4. GROUND
5. ENABLE
6. LOAD



Notes

Notes

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